

DDR4 miniDIMM Sockets, 22.5° Angled and Vertical SMT, Halogen-free

molex[®]

Angled DDR4 miniDIMM socket saves nearly half the overhead space of the vertical equivalent in enterprise computing and networking memory applications

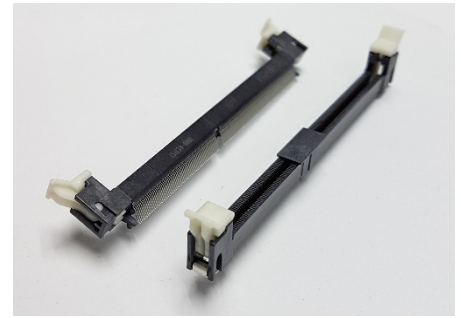
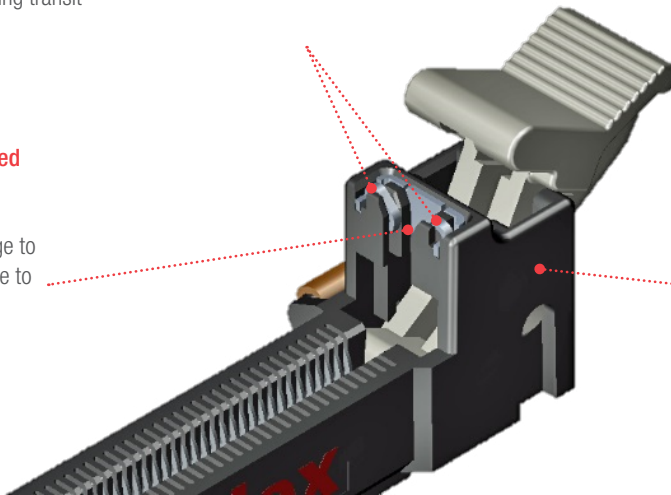
Features and Advantages

Metal grips on housing towers (patent pending)

Reduce shock or vibration to mounted memory modules during transit

Metal-reinforced latch tower housing

Prevents damage to tower bridge due to wear and tear

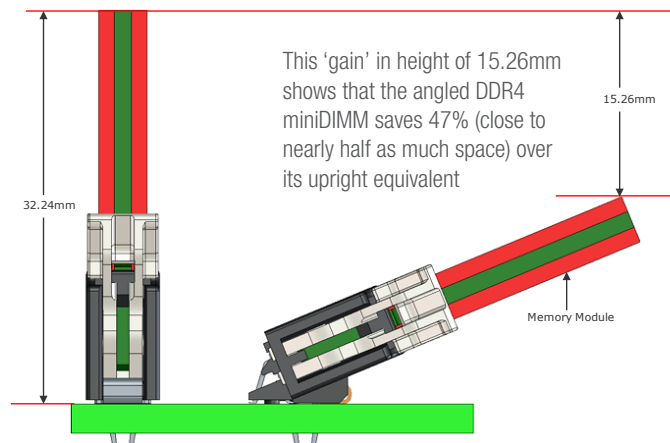


(Left to right) 22.5°-angled and Vertical SMT DDR4 miniDIMM sockets

Halogen-free housing

Meets eco-friendly environmental requirements

The 22.5° angled DDR4 miniDIMM socket offers highly robust mating and usability features for reliable operations



The 22.5° angled DDR4 miniDIMM socket save almost half as much vertical space than its upright equivalent with module mounted

Applications

Data/Communications

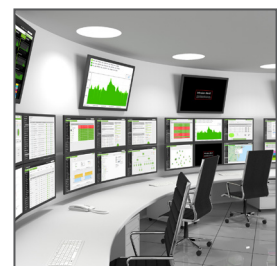
- High-end computing
- Personal computers
- RAID / Storage

Telecommunications/Networking

- Network Operations Center
- Infrastructure



Data Center



Network Operations Center

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Specifications

REFERENCE INFORMATION

Packaging: Tray
Mates With JEDEC MO-309 Memory Modules
UL File Number: E29179 (151105)
CSA File Number: 1699020 (LR19980) (151105)
Designed In: Millimeters
RoHS: Yes
Halogen Free: Yes
Glow Wire Compliant: No

ELECTRICAL

Voltage (max.): 29 Volts AC (RMS) / DC
Current (max.): 0.75A per pin
Low Level Contact Resistance:
25 milliohms (151134)
20 milliohms (151105)
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance (min.): 1 Megohm

MECHANICAL

Module Insertion Force (with latches): 150.0N max.
Module Rip-out Force (min.): 3.6kgf
Module Unmating Force: 2.02kgf (for 288 circuits)
Insertion Force to PCB: 25N (max.)
Terminal Retention Force (min.):
300gf (per pin); 8.0N (per forklock)
Latch Actuation Force (max.): 35N per latch
Durability: 25 cycles

PHYSICAL

Housing: LCP, Glass-filled, UL94V-0, Black
Latch: Polyamide, Glass-filled, UL94V-0, Black
Contact: Copper Alloy
Plating: Contact Area:
0.76 micron Gold (Au) over 1.25micron Nickel (Ni)
Solder Area: 2.54micron Tin (Sn) over
1.25micron Nickel (Ni)
PCB hold-down: 2.54micron Tin (Sn) over
1.25micron Nickel (Ni)
Operating Temperature: -55 to 85°C

Ordering Information

Series No.	Description
151134	22.5°-Angled, SMT
151105	Vertical, SMT

www.molex.com/link/ddr4.html